

ABSTRACT

A thermosetting resin film for forming a first protective film on a surface having a bump of a semiconductor wafer by being attached to the surface and being thermally
5 cured, in which when the thermosetting resin film before curing is heated at a raising temperature speed of $10^{\circ}\text{C}/\text{min}$, a time during which a viscosity at a shear rate of 1 s^{-1} is equal to or lower than $100,000\text{ Pa}\cdot\text{s}$ is equal to or longer than 500 seconds. The first protective film forming sheet is provided with the first supporting sheet, and the thermosetting resin film is provided on one surface of the first supporting sheet. A first
10 protective film is formed by thermally curing the thermosetting resin film while pressurizing at a pressure of equal to or greater than 0.1 Pa .